Product End-of-Life Disassembly Instructions

Product Category: Data Storage Devices
Marketing Name / Model **[List multiple models if applicable.]**
Name / Model #1 VLS 1002i (AG124A & AG124A#0D1)
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4(system)+2(power supply)
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		57(system)+22(power supply)
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing		0

refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

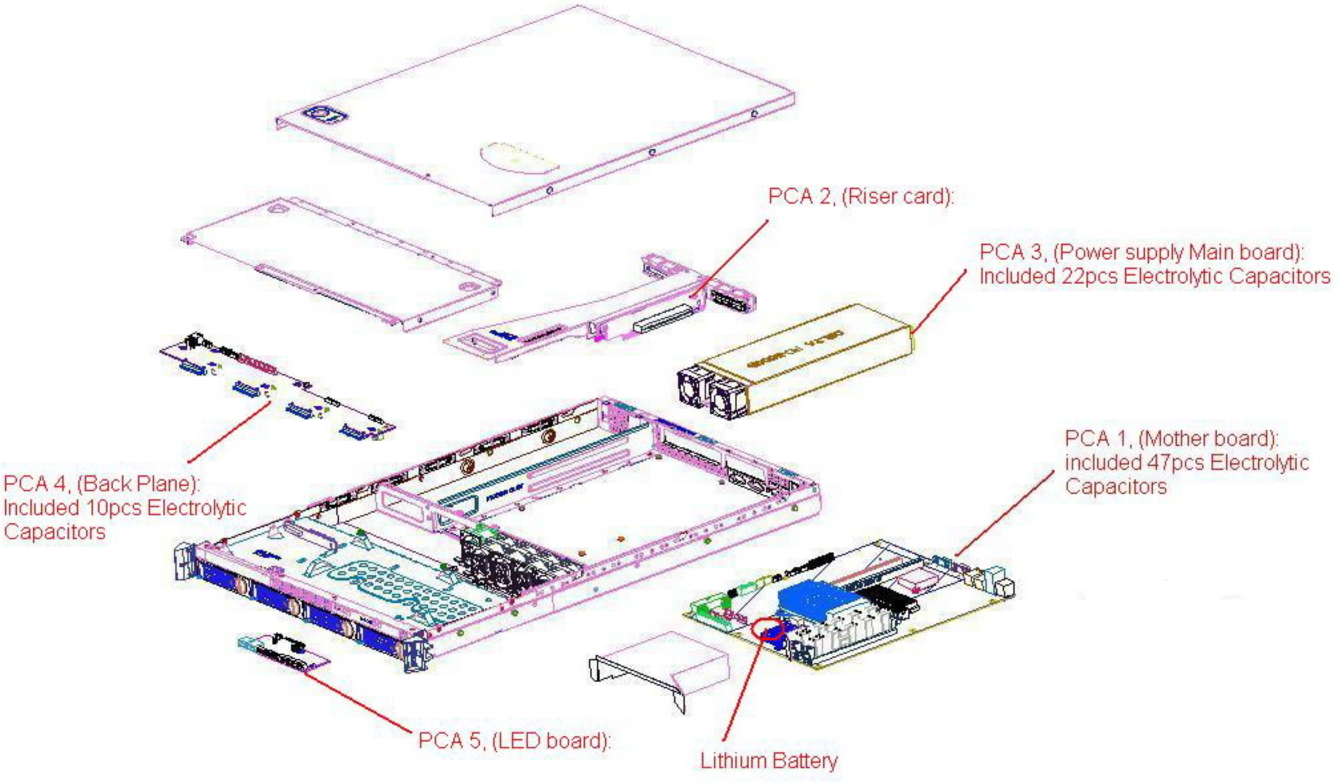
Tool Description	**Tool Size (if applicable)**
Description #1 Phillips Screwdriver	#2
Description #2 Soldering-iron	N/A
Description #3 Long nose Pliers	N/A
Description #4 Diagonal Pliers	N/A
Description #5	

3.0 Product Disassembly Process

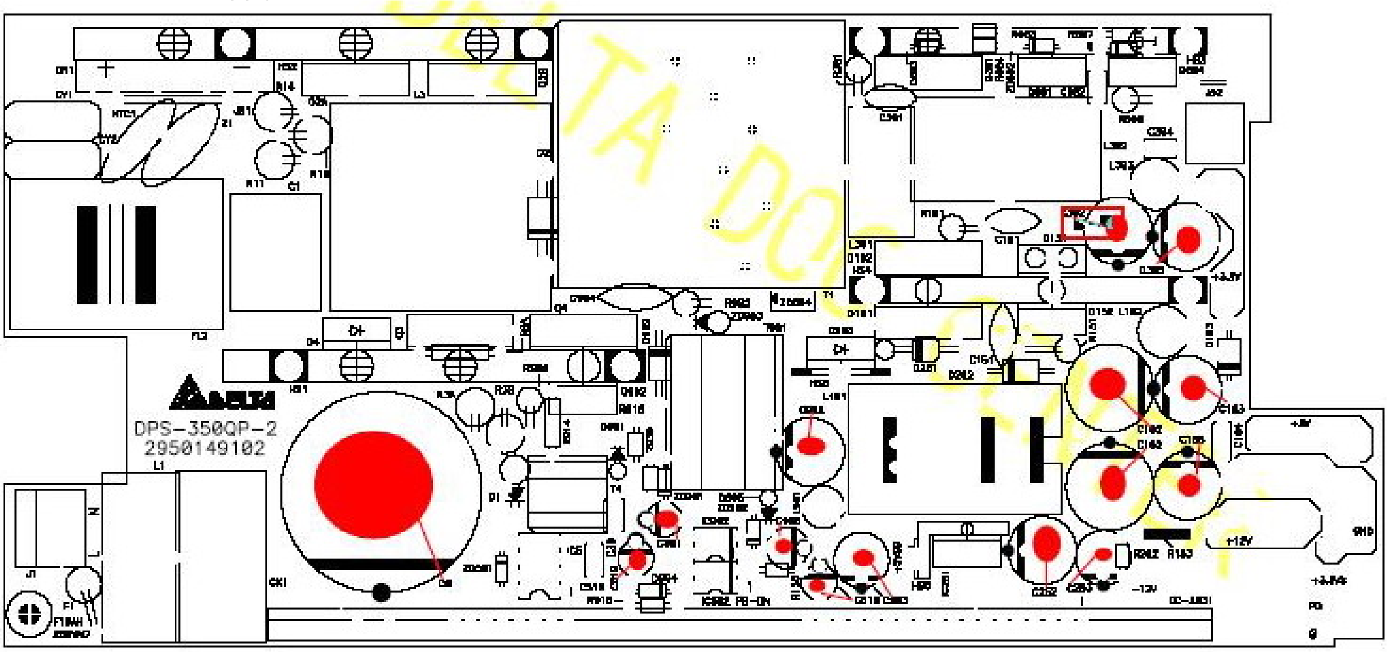
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

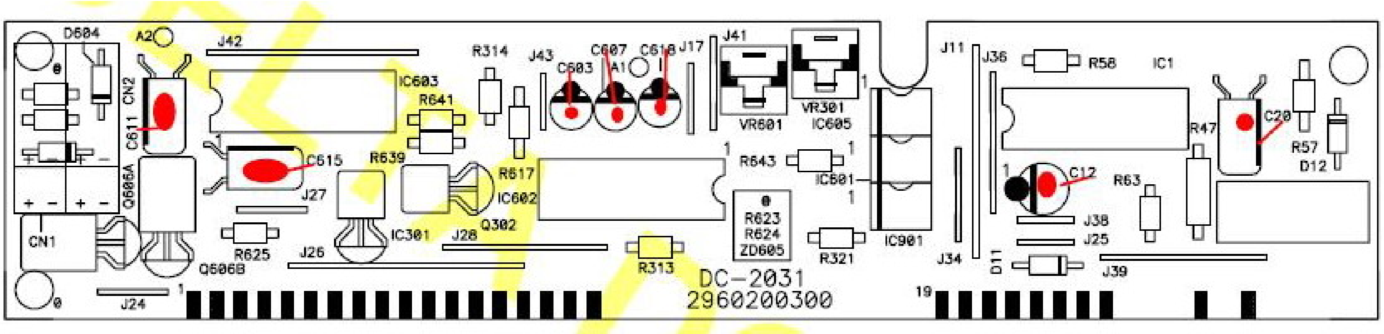
1. Release screws with Phillips screwdriver #2 then remove PCA from chasiss
2. Remove lithium coin battery from PCA with Long nose pliers
3. Remove Electrolytic Capacitors from PCA with Solder-iron or diagonal pliers
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



2 PCBs in Power supply



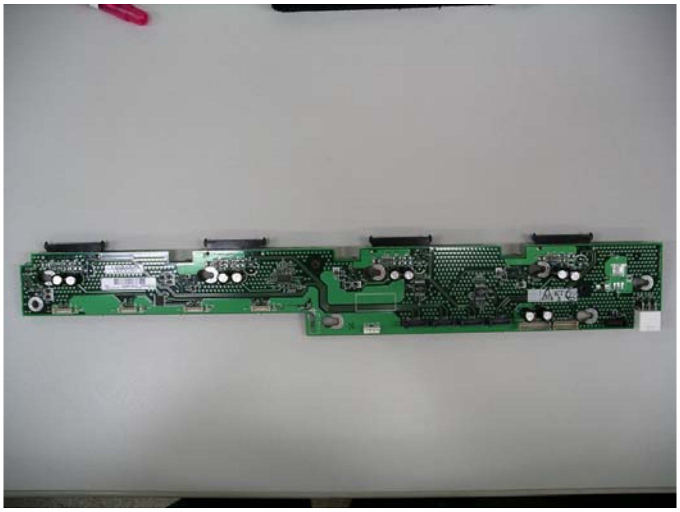


Four PCBs in whole system

LED board

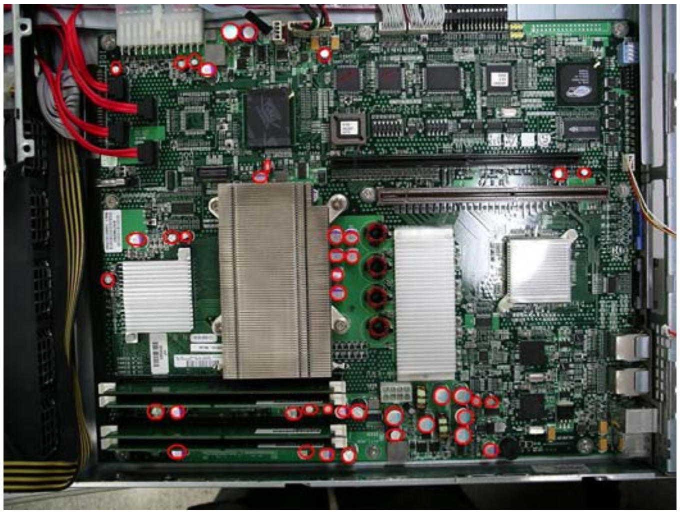
Riser Card

Mother Board



Back Plane

Total amount of Electrolytic Capacitors 57pcs



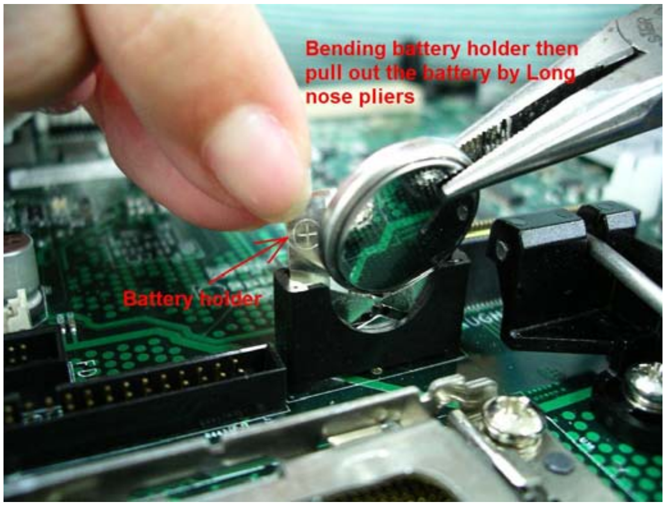
Item 1: Remove screw from PCB

Remove screw with phillips screwdriver.

See Next Page.

Item 2: Remove Lithium battery

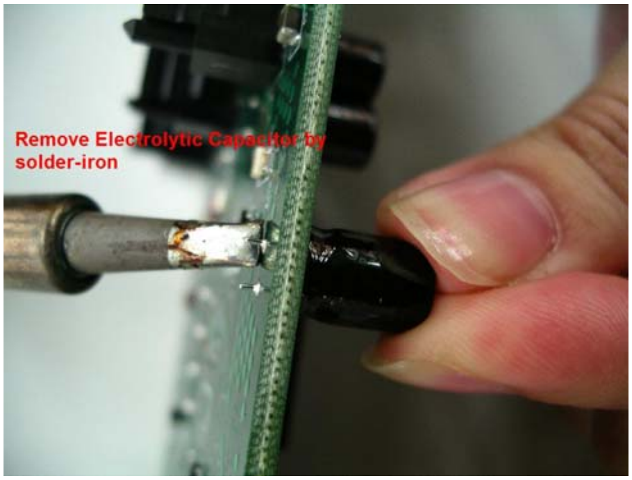
Snap Lithium battery by Long nose pliers



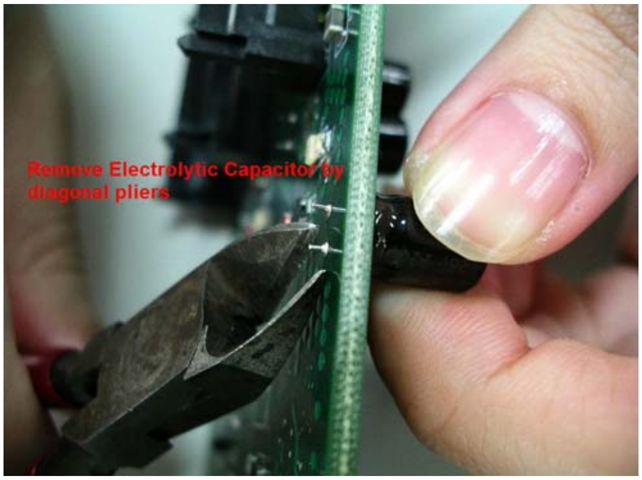
Bending battery holder then pull out the battery by Long nose pliers

Battery holder

Item 3 : Remove Electrolytic capacitor by solder-iron or diagonal pliers



Remove Electrolytic Capacitor by solder-iron



Remove Electrolytic Capacitor by diagonal pliers

End of procedure.